

# EMRA31P1J-19.200M

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## REGULATORY COMPLIANCE (Data Sheet downloaded on May 25, 2020)


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## ITEM DESCRIPTION

MEMS Clock Oscillators LVCMOS (CMOS) 1.8Vdc 4 Pad 2.5mm x 3.2mm Plastic Surface Mount (SMD) 19.200MHz  $\pm 50$ ppm over  $-40^{\circ}\text{C}$  to  $+105^{\circ}\text{C}$

## ELECTRICAL SPECIFICATIONS

|  |  |
|--|--|
| Nominal Frequency                                | 19.200MHz  |
| Frequency Tolerance/Stability                    | $\pm 50$ ppm Maximum over $-40^{\circ}\text{C}$ to $+105^{\circ}\text{C}$ (Inclusive of all conditions: Calibration Tolerance at $25^{\circ}\text{C}$ , Frequency Stability over the Operating Temperature Range, Supply Voltage Change, and Output Load Change) |
| Aging at $25^{\circ}\text{C}$                    | $\pm 1.5$ ppm Maximum First Year   |
| Supply Voltage                                   | 1.8Vdc $\pm 10\%$  |
| Input Current                                    | 4.5mA Maximum (No Load)  |
| Output Voltage Logic High (Voh)                  | 90% of Vdd Minimum (IOH = -2mA)  |
| Output Voltage Logic Low (Vol)                   | 10% of Vdd Maximum (IOL = +2mA)  |
| Rise/Fall Time                                   | 1.5nSec Typical, 3.5nSec Maximum (Measured from 20% to 80% of waveform)  |
| Duty Cycle                                       | 50 $\pm 10$ (%) (Measured at 50% of waveform)  |
| Load Drive Capability                            | 15pF Maximum   |
| Output Logic Type                                | CMOS   |
| Output Control Function                          | Power Down (Disabled Output: Logic Low)  |
| Output Control Input Voltage Logic High (Vih)    | 70% of Vdd Minimum or No Connect to Enable Output  |
| Output Control Input Voltage Logic Low (Vil)     | 30% of Vdd Maximum to Disable Output   |
| Power Down Output Enable Time                    | 5mSec Maximum  |
| Power Down Output Disable Time                   | 150nSec Maximum  |
| Standby Current                                  | 5 $\mu$ A Maximum  |
| Period Jitter (RMS)                              | 2pSec Typical, 5pSec Maximum   |
| RMS Phase Jitter (Fj = 900kHz to 7.5MHz; Random) | 0.5pSec Typical, 1pSec Maximum   |
| RMS Phase Jitter (Fj = 12kHz to 20MHz; Random)   | 1.5pSec Typical, 3pSec Maximum   |
| Start Up Time                                    | 5mSec Maximum  |
| Storage Temperature Range                        | $-65^{\circ}\text{C}$ to $+150^{\circ}\text{C}$  |

## ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

|                      |  |
|----------------------|--|
| ESD Susceptibility   | JESD22-A114, HBM, 2000V  |
| Flammability         | UL94-V0  |
| Mechanical Shock     | MIL-STD-883, Method 2002, Condition E, 10,000G                     |
| Moisture Sensitivity | J-STD-020, MSL 1   |
| Solderability        | MIL-STD-883, Method 2003 (Four I/O Pads on bottom of package only) |
| Temperature Cycling  | JESD22-A104, Condition B   |
| Vibration            | MIL-STD-883, Method 2007, Condition A, 20G                         |

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### MECHANICAL DIMENSIONS (all dimensions in millimeters)

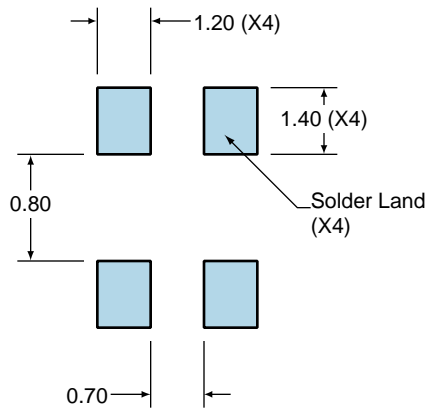


| PIN | CONNECTION             |
|-----|------------------------|
| 1   | Power Down (Logic Low) |
| 2   | Ground                 |
| 3   | Output                 |
| 4   | Supply Voltage         |

| LINE | MARKING                           |
|------|-----------------------------------|
| 1    | Ecliptek Manufacturing Identifier |

### Suggested Solder Pad Layout

All Dimensions in Millimeters



All Tolerances are  $\pm 0.1$

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## OUTPUT WAVEFORM & TIMING DIAGRAM



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## Test Circuit for CMOS Output



Note 1: An external 0.01µF ceramic bypass capacitor in parallel with a 0.1µF high frequency ceramic bypass capacitor close (less than 2mm) to the package ground and supply voltage pin is required.

Note 2: A low input capacitance (<12pF), 10X Attenuation Factor, High Impedance (>10Mohms), and High bandwidth (>300MHz) passive probe is recommended.

Note 3: Capacitance value C<sub>L</sub> includes sum of all probe and fixture capacitance. See applicable specification sheet for 'Load Drive Capability'.

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## Recommended Solder Reflow Methods



### High Temperature Infrared/Convection

|  |  |
|--|--|
| <b>Ts MAX to Tl (Ramp-up Rate)</b>         | 3°C/Second Maximum                               |
| <b>Preheat</b>                             |  |
| - Temperature Minimum (Ts MIN)             | 150°C  |
| - Temperature Typical (Ts TYP)             | 175°C  |
| - Temperature Maximum (Ts MAX)             | 200°C  |
| - Time (ts MIN)                            | 60 - 180 Seconds                                 |
| <b>Ramp-up Rate (Tl to Tp)</b>             | 3°C/Second Maximum                               |
| <b>Time Maintained Above:</b>              |  |
| - Temperature (Tl)                         | 217°C  |
| - Time (tL)                                | 60 - 150 Seconds                                 |
| <b>Peak Temperature (Tp)</b>               | 260°C Maximum for 10 Seconds Maximum             |
| <b>Target Peak Temperature (Tp Target)</b> | 250°C +0/-5°C                                    |
| <b>Time within 5°C of actual peak (tp)</b> | 20 - 40 Seconds                                  |
| <b>Ramp-down Rate</b>                      | 6°C/Second Maximum                               |
| <b>Time 25°C to Peak Temperature (t)</b>   | 8 Minutes Maximum                                |
| <b>Moisture Sensitivity Level</b>          | Level 1  |
| <b>Additional Notes</b>                    | Temperature shown are applied to body of device. |

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## Recommended Solder Reflow Methods



### Low Temperature Infrared/Convection 240°C

|  |  |
|--|--|
| <b>Ts MAX to TL (Ramp-up Rate)</b>         | 5°C/Second Maximum                                     |
| <b>Preheat</b>                             |  |
| - Temperature Minimum (Ts MIN)             | N/A  |
| - Temperature Typical (Ts TYP)             | 150°C  |
| - Temperature Maximum (Ts MAX)             | N/A  |
| - Time (ts MIN)                            | 60 - 120 Seconds                                       |
| <b>Ramp-up Rate (TL to TP)</b>             | 5°C/Second Maximum                                     |
| <b>Time Maintained Above:</b>              |  |
| - Temperature (TL)                         | 150°C  |
| - Time (tL)                                | 200 Seconds Maximum                                    |
| <b>Peak Temperature (TP)</b>               | 240°C Maximum  |
| <b>Target Peak Temperature (TP Target)</b> | 240°C Maximum 2 Times / 230°C Maximum 1 Time           |
| <b>Time within 5°C of actual peak (tp)</b> | 10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time |
| <b>Ramp-down Rate</b>                      | 5°C/Second Maximum                                     |
| <b>Time 25°C to Peak Temperature (t)</b>   | N/A  |
| <b>Moisture Sensitivity Level</b>          | Level 1  |
| <b>Additional Notes</b>                    | Temperature shown are applied to body of device.       |

### Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperature shown are applied to body of device.)

### High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperature shown are applied to body of device.)